

5. Claims:

1. A printed wiring board comprising:
  - a base substrate;
  - a land conductor layer provided on said base substrate at least in part thereof;
  - an insulating layer provided on said base substrate and said land conductor layer, having a via hole reaching said land conductor layer, and containing glass fibers;
  - a via conductor layer covering a surface of said via hole and a surface of said insulating layer at least in the vicinity of an opening of said via hole and connected to said land conductor layer; and
  - a block layer provided between the surface of said via hole and said via conductor layer for preventing migration to said via conductor layer through the glass fibers inside said insulating layer.
2. The printed wiring board according to claim 1, wherein said block layer covers an inner wall of said insulating layer at least over a range from an uppermost end to a lowermost end where said glass fibers inside said insulating layer exist.
3. The printed wiring board according to claim 2, wherein a lower end of said block layer is located above a surface of said land conductor layer.
4. The printed wiring board according to claim 1, wherein said insulating layer is formed by a resin layer in which the glass fibers are buried.
5. The printed wiring board according to claim 1, wherein said block layer is formed by an insulating layer.
6. The printed wiring board according to claim 1, wherein said block layer is formed by a resin layer.
7. A method of manufacturing a printed wiring board, comprising the steps of:

- (a) preparing a base substrate;
- (b) providing a land conductor layer on said base substrate at least in part thereof;
- (c) providing an insulating layer containing glass fibers so as to cover said base substrate and said land conductor layer;
- (d) providing a via hole in said insulating layer, said via hole reaching said land conductor layer;
- (e) providing a block layer on a surface of said via hole for preventing migration through the glass fibers inside said insulating layer; and
- (f) providing a via conductor layer covering said block layer and a surface of said insulating layer at least in the vicinity of an opening of said via hole and connected to said land conductor layer.

8. A method of manufacturing a printed wiring board, comprising the steps of:

- (a) preparing a base substrate;
- (b) providing a land conductor layer on said base substrate at least in part thereof;
- (c) providing an insulating layer containing glass fibers so as to cover said base substrate and said land conductor layer;
- (d) providing a first via hole in said insulating layer over said land conductor layer;
- (e) providing a block layer on a surface of said first via hole for preventing migration through the glass fibers inside said insulating layer;
- (f) providing a second via hole in said first via hole where said block layer is provided, said second via hole reaching said land conductor layer; and
- (g) providing a via conductor layer covering a surface of said second via hole, said block layer, and a surface of said insulating layer at least in the vicinity of an opening of said first via hole and connected to said

land conductor layer.

9. A method of manufacturing a printed wiring board, comprising the steps of:

- (a) preparing a base substrate;
- (b) providing a land conductor layer on said base substrate at least in part thereof;
- (c) providing an insulating layer containing glass fibers so as to cover said base substrate and said land conductor layer;
- (d) providing a first via hole in said insulating layer over said land conductor layer;
- (e) providing a second via hole in said first via hole, said second via hole reaching said land conductor layer, and providing a block layer on a surface of said first via hole for preventing migration through the glass fibers inside said insulating layer; and
- (f) providing a via conductor layer covering a surface of said second via hole, said block layer, and a surface of said insulating layer at least in the vicinity of an opening of said first via hole and connected to said land conductor layer.

10. The method according to claim 9, wherein the step (e) of providing said second via hole and said block layer comprises the steps of:

filling said first via hole with an insulating material; and

removing a columnar portion, extending from a surface of said filled insulating material to reach a surface of said land conductor layer, of said filled insulating material and said insulating layer between a bottom of said first via hole and the surface of said land conductor layer so as to leave said filled insulating material of a predetermined thickness on the surface of said first via hole.

11. The method according to claim 8 or 9, wherein a

lower end of said first via hole is located below a lowermost portion of said glass fibers inside said insulating layer and above a surface of said land conductor layer.